



- NOTES
1. PLATING :
Ni : 50~350 MICRON INCHES.
Au : 60~225 MICRON INCHES.
 2. SEAL AREA TO BE METALLIZED.
 3. DIE ATTACH AREA TO BE METALLIZED.
 4. LEAD RESISTANCE : 0.30 OHM MAX.
 5. WIRE BOND PAD CONNECTED TO CORRESPONDED OUTER LEADS.
 6. MISALIGNMENT OF METALLIZATION PATTERN IN CAVITY SHALL BE ACCEPTED DUE TO LAYER MISALIGNMENT.



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